

**Amendments to the Specification**

Please replace the paragraph beginning on page 12, line 15 with the following amended paragraph:

The Al base material used in this embodiment is commercially available, industrial-use pure Al (A1050). The solder is a commercially Al-10Si-1.5Mg-0.1Bi-based solder foil (4104-equivalent, solidus temperature: 832 K (559 deg C), liquidus temperature: 864 K (591 deg C), thickness: 100 microns). The Ag used as the insert material is a pure silver foil (99.99% purity), which is clad to oxygen-free steel [?copper?—transl.] (C1020) and is commercially available as an Ag-clad Cu plate (Ag thickness: 100 microns, Cu thickness: 3 mm).

Please replace the paragraph beginning on page 19, line 27 with the following amended paragraph:

For this embodiment, a commercially available industrial pure aluminum (A1050) was used for the Al base material. The Ag used as the insert material is a pure silver foil (99.99% purity), which is clad to oxygen-free steel [?copper?—transl.] (C1020) and is commercially available as an Ag-clad Cu plate (Ag thickness: 100 microns, Cu thickness: 3 mm).